AMENDMENTS TO THE CLAIMS

Claims 1-31 (Canceled)

Claim 32 (New) A method of processing a substrate, comprising:

providing a substrate having an interconnection groove formed in a surface of the substrate, a barrier layer formed on the surface of the interconnection groove, and a seed layer formed on the barrier layer;

plating the substrate to reinforce an incomplete portion of the seed layer; and then

plating the substrate by supplying a first current to the reinforced seed layer in a plating solution containing metal ions and then supplying a second current to the reinforced seed layer in the plating solution, the second current being larger than the first current.

Claim 33 (New) A method according to claim 32, wherein the metal ions comprise copper ions.

Claim 34 (New) A method according to claim 32, wherein said supplying of the second current is for about 80 to about 110 seconds.